

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Appl. No.: | 10/611,480 | Confirmation No. 3306 |
| Applicant: | Sean Michael Malolepszy et al. | |
| Filed: | July 1, 2003 | |
| TC/A.U.: | 3729 | |
| Examiner: | Arbes, Carl J | |
| Customer No.: | 23494 | |
| Docket: | TI-33434.1 | |

EX PARTE QUAYLE AMENDMENT

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the Office action of February 22, 2006, applicants amend the application as follows:

Amendments to the Specification begins on page 2 of this paper.

Amendments to the Claims, as reflected in the listing of claims, begin on page 3 of this paper.

Remarks/Arguments begin on page 6 of this paper.

Appl. No. 10/611,480
Amdt. dated June 21, 2006
Reply to Office action of Feb. 22, 2006

Amendments to the Specification:

Please replace the title of this application with the following new title:

Wirebonder to Bond an IC Chip to a Substrate

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:1.

1-16. (canceled)

17. (original) A wirebonder adapted to wire bond an integrated circuit chip to a substrate, the substrate having formed thereon a plurality of conductive traces, at least one of the conductive traces having a bond region containing a bond surface, the machine comprising:

a support structure positioning device;

a conditioning device positioned adjacent the support structure positioning device, the conditioning device and the support structure being movable relative to one another in a direction normal to the support structure, the conditioning device comprising:

a member;

a raised boss on the member, the raised boss being configured to compress bond surfaces on a top surface of the support structure when the conditioning device is engaged with the support structure;

a cavity located so as to receive therein an integrated circuit chip mounted on said support structure when the flexible member is engaged with the support structure; and

a bond wire capillary positioned over the circuit board clamp.

18. (original) The machine of claim 17 further comprising a heater connected to the conditioning device.

19. (original) The machine of claim 17 further comprising a vibrator connected to the conditioning device.

20. (original) The machine of claim 17 further comprising a servo motor attached to the conditioning device, the servo motor moving the conditioning device relative the support structure positioning device.

Remarks/Arguments

Applicants thank Examiner Arbes for his careful examination of this application and for allowing claims 17-20. In response to the Office Action of February 22, 2006, applicants amend this application as follows:

1. The title of this application is changed to -- Wirebonder to Bond an IC Chip to a Substrate.
2. Claims 1-16 are canceled from this examination.

Applicants respectfully submit that as amended, this application is in allowable form.

Respectfully submitted,

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